**In the Specification**

**Please delete the paragraph beginning on page 8, line 3 and replace it with the following paragraph:**

A final surface preparation step may be to pass the workpiece or wafer through the interface(s) vertically, horizontally, or at any other orientation. The rate of extraction should be controlled to prevent excessive stirring of the two or more fluids. Preferably, the interface should remain fairly flat during the extraction process to take advantage of the differing solubility characteristics of the fluids being utilized. In addition, the rate of extraction can be adjusted to take advantage of any surface tension gradient that exists between the two fluids to sweep the workpiece free of the higher density fluid and/or other contaminants. It is not required that the workpiece ~~by~~be dried via the pumping action of the surface tension gradient although this may be an incidental result. Agitation or energy input which is periodic in time, or any combination thereof may be imparted on the two or more fluids followed by fluid settling allows the solutions to separate and could be included as part of the process prior to passing the workpiece through the interface(s). Additionally, mixing the fluids at an elevated temperature for a portion of the process followed by a temperature reduction to cause separation of the fluids could be included as part of this process prior to passing the workpiece or wafer through the fluid interface.

**Please delete the paragraph beginning on page 8, line 3 and replace it with the following paragraph:**

An example of such an apparatus is shown in Fig. 1 wherein a vertically oriented vessel 10 has at least one bottom drainage/fill means 20 and another more centrally located drainage/fill means 30. Most preferably, drainage/fill means 30 is located above bottom drainage/fill means 20. A workpiece 40 having foreign material 45 is passed through the fluid interface into the bottom portion of vessel 10, in this case into the chloroform layer or HDL 50. The water layer or LDL 60 has a higher affinity for the water and water soluble impurities such that foreign material 45 remains in the water layer. Workpiece 40 may be placed on a mechanical or lever means 70 in order to position, raise and lower workpiece 40 within vessel 10. The water layer or LDL 60 may be removed through drainage/fill means 30 prior to removing workpiece 40. Alternatively, chamber 10 may ~~having~~have a point of entrance in the portion of vessel 10 containing the water layer and a point of exit in the portion of vessel 10 containing the HDL.

**Please delete the paragraph beginning on page 11, line 15 and replace it with the following paragraph:**

In practicing the preferred embodiments of the present invention, the apparatus of Fig. 1 may also be used with an etching system utilizing the fluid interface methodology disclosed above. Workpiece 40 is first soaked in the bottom portion of vessel 10 wherein HDL 50 is capable of etching a layer from a surface of workpiece 40~~ is located~~. A LDL 60 floating above HDL 50 is preferably a fluid which has a low affinity for the layer to be removed such that upon raising workpiece 40 above the fluid interface, the process of etching the workpiece stops almost immediately. Upon soaking workpiece 40 for an

effective period of time to remove the unwanted layer, workpiece 40 is passed through the fluid interface into LDL 60 which preferably terminates any reaction process and in some instances may act as a rapid etch stop.